

**AMENDMENTS TO THE DRAWINGS**

Applicants hereby submit Replacement Sheets for FIGS. 1-4.

Attachment: Replacement Sheets

## **REMARKS**

### **Status of the Application**

Claims 1-13 are the claims that have been examined in the application. Claim 10 is objected to because of informalities. Claims 1-6 are rejected under 35 U.S.C. § 102(b) as being anticipated by Hanaoka et al. (US Publication 2002/0030245). Claims 7-13 are rejected under 35 U.S.C. § 103 (a) as being unpatentable over Hanaoka in view of Wood et al. (US Publication 2004/0207081).

By this Amendment, Applicants hereby amend claims 7-13, cancel claim 9 and add new claims 14-17.

### **Preliminary Matters**

The Examiner has acknowledged the claim for foreign priority and confirmed receipt of the certified copy of the priority document.

The Examiner has considered and initialed the Information Disclosure Statements filed on September 25, 2006 and January 8, 2007.

### **Drawing Objection**

*The drawings are objected to by the Examiner because the Examiner argues that FIGS. 1-4 should be labeled "PRIOR ART" as the figures only illustrate that which is old.*

Applicants hereby submit replacement FIGS. 1-4 in order to correct the noted deficiency.

### **Claim Objection**

*Claim 10 is objected to because of informalities.*

The Examiner object to claim 10, alleging that the phrase "said expose wiring portion" in lines 13-14 lacks antecedent basis. Applicants hereby amend claim 10 to correct the noted deficiency.

**Claim Rejections -- 35 U.S.C. § 102(b)**

*Claims 1-6 are rejected under 35 U.S.C. § 102(b) as being anticipated by Hanaoka et al. (US Publication 2002/0030245).*

Claim 1 recites, in part, “a through extension wiring with which said through hole is filled and which is formed on one surface of said through wiring board to extend to a position at a predetermined distance from said through hole.” The Examiner alleges that Hanaoka discloses each of the elements of claim 1. Applicants respectfully disagree.

Hanaoka discloses a method of fabricating a semiconductor device which includes forming a through hole in a semiconductor element which has electrodes on a first surface, and forming a conductive layer which is electrically connected to the electrodes and is provided from the first surface to a second surface through the formed hole. Further, the conductive layer allows for the electrodes be separated by a distance different from a distance between the portions disposed within the formed holes.

Applicants submit that two main differences exist between Hanaoka and the wiring board recited in claim 1 and exemplified in FIG. 5. First, the through extension wiring recited in claim 1 fills the through hole. According to Hanaoka, in FIG. 1 and the paragraphs describing the same, the through hole is not filled, but remains open. The Examiner alleges that the conductive layer 8 in Hanaoka corresponds to the through extension wiring recited in claim 1. However, the conductive layer 8 cannot disclose each of the features of the through extension wiring, since the conductive layer does not fill the hole.

Therefore, claim 1 is patentable over the applied art. Claims 2 and 3 are patentable at least by virtue of their dependency from claim 1.

Independent claims 4-6 recite elements similar to claim 1 and are patentable for reasons analogous thereto.

**Claim Rejections -- 35 U.S.C. § 103(a)**

*Claims 7-13 are rejected under 35 U.S.C. § 103 (a) as being unpatentable over Hanaoka in view of Wood et al. (US Publication 2004/0207081).*

As amended, claim 7 recites “a first reroute wiring which comes in contact with a first exposed wiring portion of said through wiring and which is formed on at first surface of said through wiring board to extend on said first surface of said through wiring board to a position at a predetermined distance from said first exposed wiring portion” and “a second reroute wiring which comes in contact with a second exposed wiring portion of said through wiring on a second surface of said through wiring board and which is formed on the second surface of said through wiring board to extend to a position at a predetermined distance from said second exposed wiring portion.” The Examiner alleges that a proposed combination of Hanaoka and Wood renders claim 7 obvious. Applicants respectfully disagree.

As noted by the Examiner, Hanaoka fails to disclose that the reroute wiring comes into contact with an exposed wiring portion of said through wiring. However, the Examiner, alleges that Wood cures this deficiency and that the resulting combination would render claim 1 obvious. See the rejection of claim 9 on page 7 of the Office Action. Wood discloses that a connection to contacts 50 and 52 may be connected to one end of conductive member 38. However, Wood fails to disclose that reroute wirings are connected to two exposed wiring portions of a through wiring. Rather, Wood is limited to connection to a single exposed wiring. Therefore, Wood cannot cure the deficiency noted with respect to Hanaoka regarding claim 7, and the combination cannot render claim 7 obvious.

Therefore, claim 7 is patentable over the applied art. Claim 8 is patentable over the applied art.

Applicants hereby amend claims 10, 12 and 13 to recite similar elements to amended claim 7, and claims 10, 12 and 13 are patentable for reasons analogous thereto.

**New Claims**

Applicants hereby add new claims 14-17, which depend from claims 1, 4, 5 and 6, respectively. Claims 14-17 are patentable at least by virtue of their respective dependencies.

**Conclusion**

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,

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